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WAFER INTEGRATED-CIRCUIT DEVICE

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[There are no amendments to this patent.]

Claims

1. A wafer integrated-circuit device characterized by the fact that it consists of a wafer (1), in which a circuit (2) for a system is formed, and a wafer (4), in which a circuit (5) having the function of constituting a wafer integrated circuit is formed; with said circuits (2) and (5) of two wafers being mutually connected, so that a system is realized.

2. A wafer integrated-circuit device characterized by the fact that it consists of a wafer (1), in which a circuit (2) for a system is formed, and a wafer (4), in which a circuit (5) having the function of constituting a wafer integrated circuit is formed; with these being laminated on the front and the front, the back and the back, or the front and the back; and with said circuits (2) and (5) of two wafers being mutually connected, so that a system is realized.

3. A wafer integrated-circuit device characterized by the fact that a wafer (1), in which a circuit (2) for a system is formed, and several wafers or chips (4, 10), in which a circuit having the function of constituting a wafer integrated circuit is

formed, are laminated; with these circuits being mutually connected, so that a system is realized.

4. A wafer integrated-circuit device characterized by the fact that a wafer (1), in which a circuit (2) for a system is formed, a wafer (4), in which only wiring is formed, and a chip or wafer (10), in which a circuit having the function of constituting a wafer integrated circuit is formed, are laminated; with these circuits being mutually connected, so that a system is realized.

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